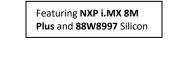
Summit SOM 8M Plus



i.MX 8M Plus with Dual-Band 2x2 Wi-Fi 5 + Bluetooth 5.3 System-on-Module

SECURE, SMART, AND CONNECTED IOT: POWERFUL NXP EDGE PROCESSING WITH NXP WI-FI AND BLUETOOTH







2x2 Wi-Fi 5 (**802.11ac**) and **Bluetooth 5.3**

1.6 GHz quad-core Cortex-A53 and 800 MHz Cortex-M7

- Our customers asked for a high-performance, secure, and robust IoT SoM that's rugged, simplifies their BOM, has reliable connectivity, and is globally certified. One with a proven security architecture, long term software support, security fixes, and device management. Our new Summit SOM 8M Plus is powered by **NXP's innovative i.MX 8M Plus** processor and **88W8997** wireless silicon coupled with onboard NXP PMICs (PCA9450CHN and PM823UK), performance LPDDR4 RAM, and eMMC 5.1 storage. We combine this with our long-term support Summit Yocto Linux and Zephyr RTOS, **secure enclave**, and **Summit Linux FIPS Core Crypto** to offer a comprehensive hardware and software solution throughout your product's lifecycle.
- Powerful Heterogenous Multiprocessing: 1.6 GHz quad-core Cortex-A53 microprocessor and 800 MHz Cortex-M7 microcontroller allow you to run Linux and an RTOS on dedicated, hardware-firewalled subsystems.
- Dedicated Machine Learning: High-performance edge machine learning via an integrated neural processing unit, delivering up to 2.3 TOPS.
- Diversity of Hardware Interfaces: Wide selection of display, network, data, audio and camera interfaces
- Virtualization: Quad core MPU can run multiple firewalled Linux instances, i.e. separate instances for user interface, connectivity, and others
- Secure and Encrypted Boot: Robust, secure, and optionally encrypted boot mechanism to ensure only intended software boots on your device.
- Advanced DVK: Reference designs for display, camera, audio, LTE, GPS, power consumption profiling, PoE, battery usage, battery charging, USB 3.0 power, and a Bluetooth 5.2 module integration supporting LE coded/Long Range.

FEATURES AT A GLANCE



RELIABLE CONNECTIVITY: WI-FI 5 2X2 MIMO AND BT 5.3

PA/LNA provide excellent connectivity in difficult environments, plus enterprise support for better roaming, encryption, single SKU support, hardware LTE coex, and more.

ML, GRAPHICS, VIDEO, VISION, AND AUDIO - UP TO 3 DISPLAYS

2.3 TOPS Machine Learning/Neural Processing Unit, up to 1200p60 or 4Kp30 displays, 2 shader GPU, 1080p60 multi codec encode and decode VPU, 2 MIPI-CSI camera interfaces, dedicated Image Signal Processing up to 12 MP, HiFi4 audio DSP

SECURE ENCLAVE AND SECURE BOOT POWERED BY I.MX 8M PLUS Dedicated on-board security hardware, secure boot Linux, and high-performance and flexible secure storage system for passwords, certificates, and data storage.



Contact Sales -

ROBUST SOFTWARE AND SPEED TO MARKET

LTS Summit Yocto Linux and Zephyr RTOS with CVE remediation available, plus NXP's base Linux and FreeRTOS releases

GLOBAL APPROVALS

Carries several modular FCC, IC, CE, RCM, MIC and Bluetooth SIG approvals. Ship a single SKU worldwide with Adaptive World Mode.

PERSONAL SUPPORT FROM DESIGN TO MANUFACTURE

Our industry-renowned support and field application engineering team is passionate about helping you speed your design to market.

Americas:+1 262 375 4400Europe:+44 1628 940 ext. 958Hong Kong:+852 2762 4823

2x2 Wi-Fi 5 (802.11ac) with MIMO

- Supports Adaptive World Mode: ship a single SKU worldwide
 Supports the latest WPA3-Personal, WPA3-Enterprise, and WPA3-
- Enterprise SuiteB 192-bit security standards.
 Hardware LTE coexistence integrates seamlessly w/ LTE modules
- Hardware LTE coexistence integrates seamlessly w/ LTE module
 PCIE 2.0 (WLAN)/UART(BT) or SDIO 3.0 (WLAN)/UART(BT)
- Bluetooth 5.3 Classic BT & Bluetooth Low Energy (LE), inc. 2MPHY
- Integrated Wi-Fi + Bluetooth coexistence for seamless connectivity
- Industrial Temperature Rating (-30° to +85 °C)
- Multiple high performance memory options: 512MB LPDDR4 / 8GB eMMC 1GB LPDDR4 / 8GB eMMC 2GB LPDDR4 / 16GB eMMC 4BG LPDDR4 / 32GB eMMC For other sizes of RAM / storage, please contact sales.
- Extensive range of pre-certified antennas
- Rugged Design solder down 40mm x 47mm form factor
- Power Efficient: NXP PMICs, power optimized LPDDR4 and eMMC memory. Core shut off, clock/voltage scaling, low power interfaces, power optimized single stream Wi-Fi mode enable highly optimized power consumption.
- Full Product Lifecycle Management with our future Device Management solution to update devices in the field and long-term hardware availability
- Hardware Connectivity Roadmap: pin-compatible connectivity updated Summit SOM 8M Plus modules will be available in the future as NXP updates their 2x2 Wi-Fi-BT combo silicon to the latest standards.



Smart Buildings and Appliances



APPLICATION AREAS



Industrial IoT, Vision Systems



Printers and Scanners



For documentation, software, sample apps and more visit: http://www.lairdconnect.com/summit-som-8m-plus

KEY SPECIFICATIONS

FEATURE	SPECIFICATION	
Microprocessor	4x Cortex [®] -A53 cores @ 1.6 GHz	
Microcontroller	1x Cortex [®] -M7 core @ 800 MHz	
Audio	Tensilica [®] HiFi 4 DSP	
Graphics	GC7000UL with 2 shaders for 3D and GC520L for 2D	
Machine Learning	Neural Processing Unit (NPU) with 2.3 TOP/s	
RAM	512MB, 1GB, 2GB and 4GB; For other sizes please contact s	ales
Storage	8GB, 16GB and 32GB; For other sizes please contact sales	
Neural Processing Unit	Keyword detect, noise reduction, beamformingSpeech recognition (i.e. Deep Speech 2)	 Image recognition (i.e. ResNet-50)
Graphics Processing Unit	 166 million triangles/sec 1.0 giga pixel/sec 10 giga pixel/sec 0 penGL ES 1.1, 2. 	 2D acceleration .0, 3.0, OpenCL 1.2, Vulkan
Video Processing Unit	Video Decode	Video Encode
	 1080p60 HEVC/H.265 Main, Main 10 (up to level 5.1) 	 1080p60 AVC/H.264 encoder
	 1080p60 VP9 Profile 0, 2 	 1080p60 HEVC/H.265 encoder
	 1080p60 VP8 	
	 1080p60 AVC/H.264 Baseline, Main, High decoder 	
Display Interfaces	 1x MIPI DSI, up to UWHD and WUXGA 	 1x HDMI 2.0a Tx, up to 4kp30
	 1x LVDS Tx, up to 1920x1080p60 	
Camera	2x 4-lane MIPI CSI	
Image Signal Processor	375 Mpixel/s HDR ISP supporting configurations, such as 12	MP@30fps, 4kp45, or 2x 1080p80
Audio Interfaces	 SPDIF input and output 	 ASRC
	 Six external SAI modules supporting I2S, AC97, TDM, 	 eARC/ARC (HDMI)
	codec/DSP, and DSD interfaces	 8-channel PDM mic input
Input/Output	 2x USB 3.0/2.0 Dual-Role with PHY 	 4x UART 5 Mbit/s
	 2x Gbit Ethernet with IEEE[®] 1588, AVB (One also 	 6x I2C
	supports TSN)	 3x SPI
	 2x CAN/CAN FD 	 1x SDIO 3.0/eMMC 5.1
Wi-Fi	Wi-Fi 5 (802.11ac)	
Bluetooth®	v5.3	
Frequency	Dual-Band 2.4GHz & 5GHz	
Transmit Power	+ 18 dBm (maximum)	
Antenna Options	2x U.FL connectors for external antennas	
Raw Data Rates (Air)	Wi-Fi 5 866.7Mbit/s - MCS9, 2 Spatial Streams, 80MHz, 256	QAM, SGI
Wi-Fi 5 (802.11ac)	 IEEE 802.11 a/b/g/n/ac 	 MIMO, OFDMA
	 20, 40 & 80MHz bandwidth support 	 Transmit Beamforming
Bluetooth	 Classic Bluetooth – BR / EDR 	 Up to 16 Bluetooth LE connections
	 2 x WideBand Speech (WBS) links 	 LE Secure Connections
	 Central / Peripheral Modes 	 2MPHY
	3.3V	
Dimensions	40mm x 47 mm x 4.6 mm (SIP Modules)	
Temp Range	-30°C to +85°C	
Lead Free	Lead-free and RoHS-compliant	
Development Kit	Development board, accessories, and evaluation software	
Bluetooth [®] SIG	Bluetooth 5.3	
Approvals	FCC/IC/CE/MIC/RCM	
••		
		el)
Module, Summit SOM 8N	/I Plus, Quad Core CPU, 1GB LPDDR4, 8GB eMMC (Tape/Reel)	
Module, Summit SOM 8M Plus, Quad Core CPU, 2GB LPDDR4, 16GB eMMC (Tape/Reel)		
Module, Summit SOM 8M Plus, Quad Core CPU, 4GB LPDDR4, 32GB eMMC (Tape/Reel)		
	/ Plus, Quad Core CPU, 2GB LPDDR4, 16GB eMMC (Cut Tape)	
,	A Plus, Quad Core CPU, 4GB LPDDR4, 32GB eMMC (Cut Tape)	
Module, Summit SOM 8N		
Development Kit, Summi	t SOM 8M Plus, Quad Core CPU, 512MB LPDDR4, 8GB eMMC	
Development Kit, Summi Development Kit, Summi		
	Microprocessor Microcontroller Audio Graphics Machine Learning RAM Storage Neural Processing Unit Graphics Processing Unit Video Processing Unit Video Processing Unit Video Processing Unit Display Interfaces Camera Image Signal Processor Audio Interfaces Camera Image Signal Processor Audio Interfaces Input/Output Wi-Fi Bluetooth® Frequency Transmit Power Antenna Options Raw Data Rates (Air) Wi-Fi 5 (802.11ac) Bluetooth Bluetooth Signal Dimensions Temp Range Lead Free Development Kit Bluetooth® SIG Approvals ion the Summit SOM 8N Module, Summit Som 8N M	Microprocessor 4x Cortex*-A53 cores @ 1.6 GHz Microcontroller 1x Cortex*-M7 core @ 800 MHz Audio Tensilica* HiFi 4 DSP Graphics GC7000UL with 2 shaders for 3D and GC520L for 2D Machine Learning Neural Processing Unit (NPU) with 2.3 TOP/s RAM \$12MB, 1GB, 2GB and 4GB; For other sizes please contact sales Storage 86B, 1GGB and 32GB; For other sizes please contact sales Neural Processing Unit Keyword detect, noise reduction, beamforming Speech recognition (i.e. Deep Speech 2) Graphics Processing Onit 1.0 giga pixel/sec OpenGL ES 1.1, 2 Video Processing Unit Video Decode 1080p60 HVC/H.265 Main, Main 10 (up to level 5.1) Nigop60 AVC/H.264 Baseline, Main, High decoder 1080p60 AVC/H.264 Baseline, Main, High decoder Display Interfaces 1x MIPI DSI, up to UWHD and WUXGA X 4-lare MIPI CSI Size xetmal SAI modules supporting I2S, AC97, TDM, codec/DSP, and DSD interfaces Input/Output 2x USB 3.0/2.0 Dual-Role with PHY 2x Gbit Ethernet with IEEE 1588, AVB (One also supports TSN) Z 4-Jare MiPI CSI Size xetmal SAI modules supporting 2.5 Ac97, TDM, codec/DSP, and DSD interfaces Input/Output 2x USB 3.0/2.0 Dual-Role with PHY 2x Gbit Ethernet with IEEE 1588, A

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